

LCFI Mechanical Studies

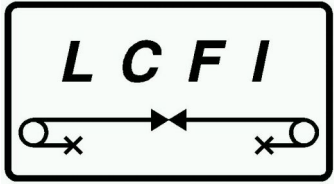
A Vertex Detector for the ILC

Ringberg, 2006

Joel Goldstein

CCLRC Rutherford Appleton Laboratory

For the LCFI Collaboration



Outline



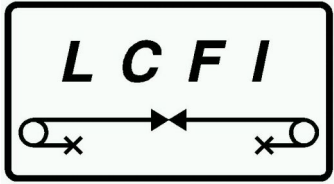
1. Thin Ladders $\sim 0.1\% X_0$

- Materials and designs for $\Delta T \approx 70\text{K}$
- Uniform material in tracking volume
- *CCDs routinely thinned to epitaxial layer*

2. Cooling

- Check gas cooling capability

3. Status and Plans



Mechanical Options



Target of $\sim 0.1\%$ X_0 per layer
(100 μm silicon equivalent)

1. Unsupported Silicon

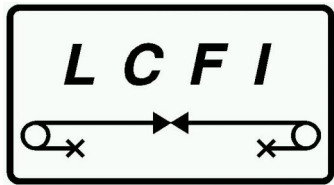
- Longitudinal tensioning provides stiffness
- No lateral stability
- Not believed to be promising

2. Thin Substrates

- Detector thinned to epitaxial layer (20 μm)
- Silicon glued to low mass substrate for lateral stability
- Longitudinal stiffness still from tension

3. Rigid Structures

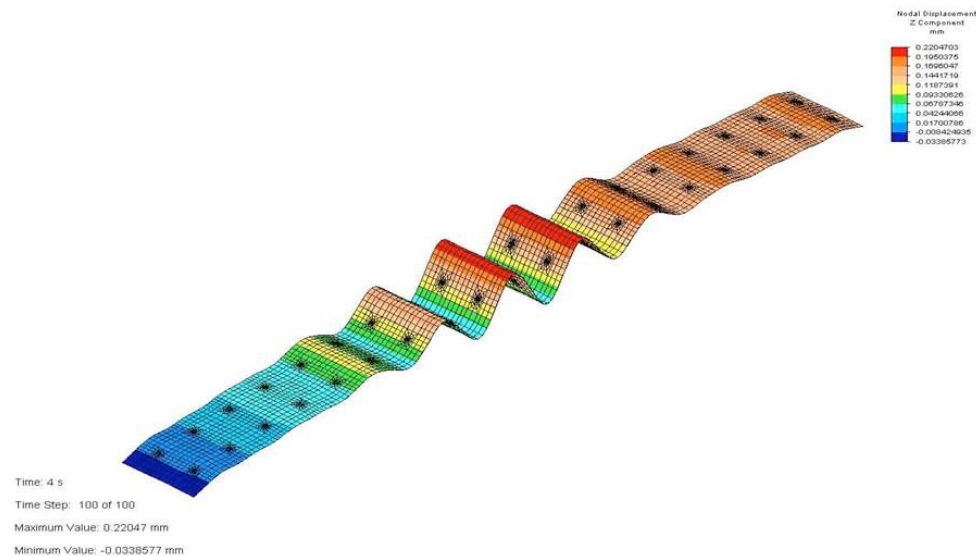
- No tensioning required



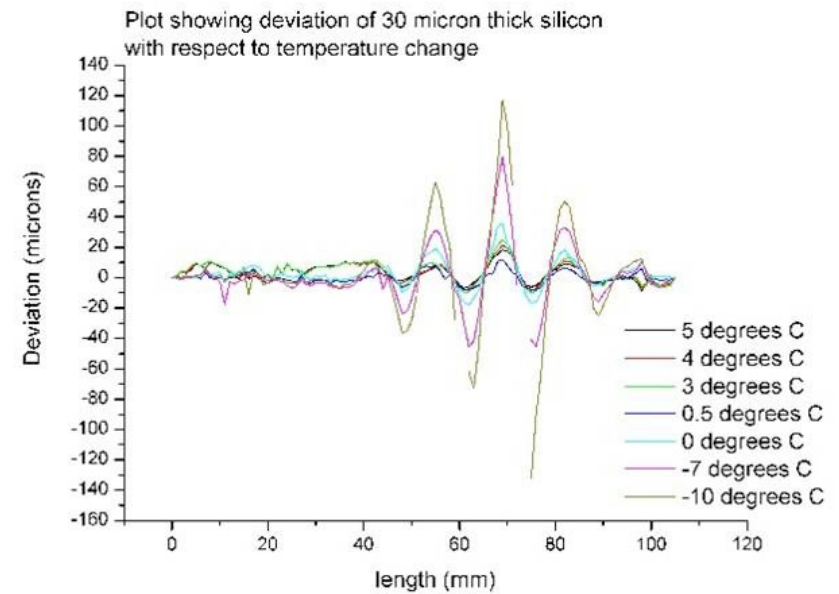
Mechanical Methods



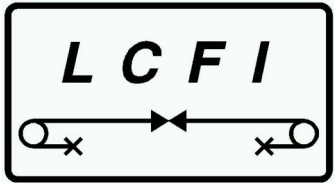
FEA Simulations



Physical Prototyping



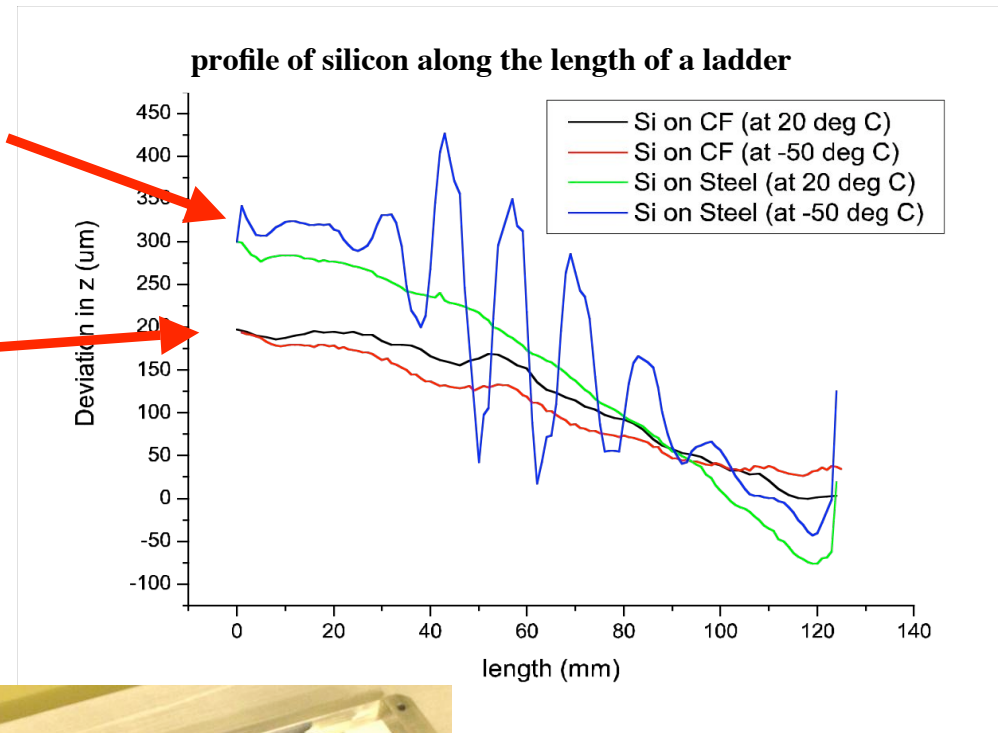
- Laser survey system

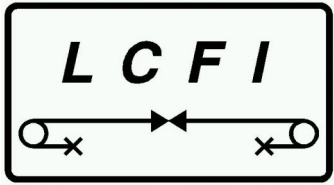


Thin Substrates



- Beryllium
 - CTE mismatch too large
- Carbon fibre
 - 0.09% X_0 prototype
- Ceramics
 - Fragile

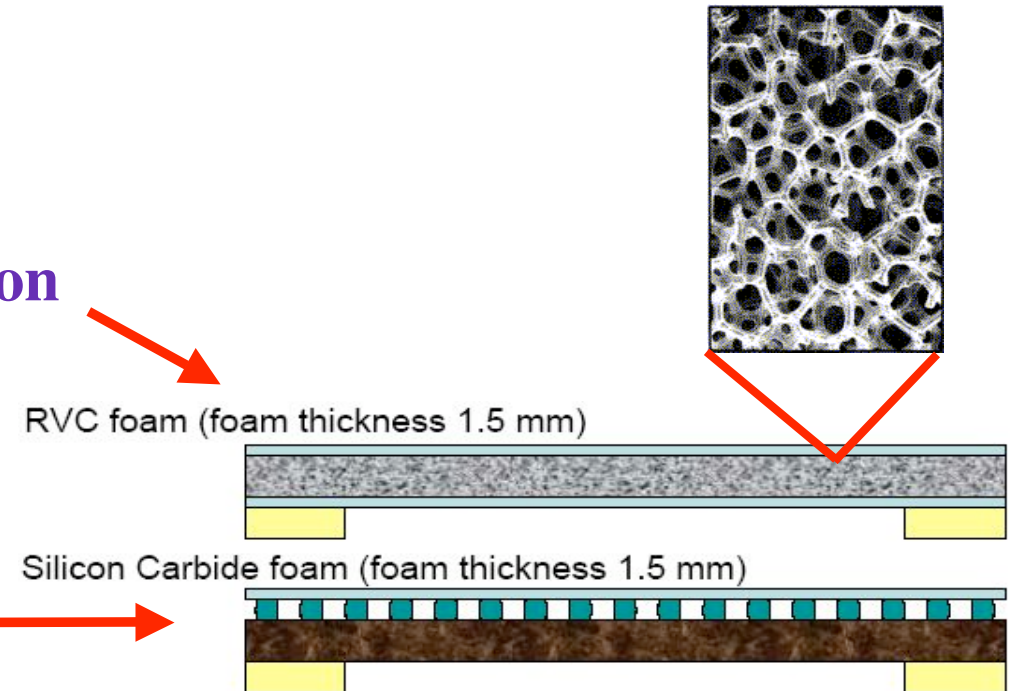




Rigid Structures: Foams

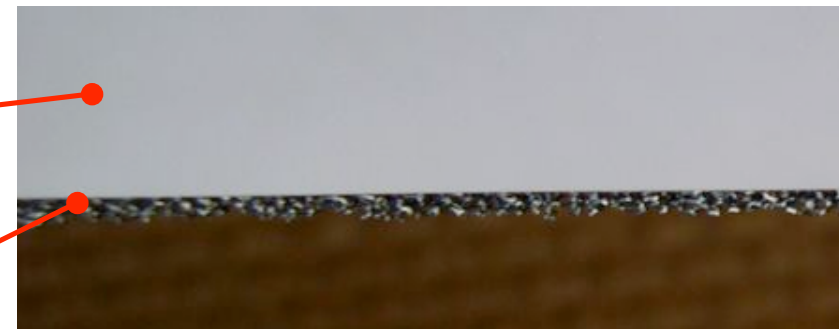


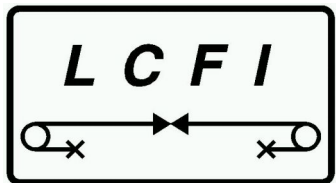
- **3% RVC Sandwich**
 - 0.09% X_0
 - Working on glue application
- **8% Silicon Carbide**
 - 0.14% X_0
 - 3-4% believed possible



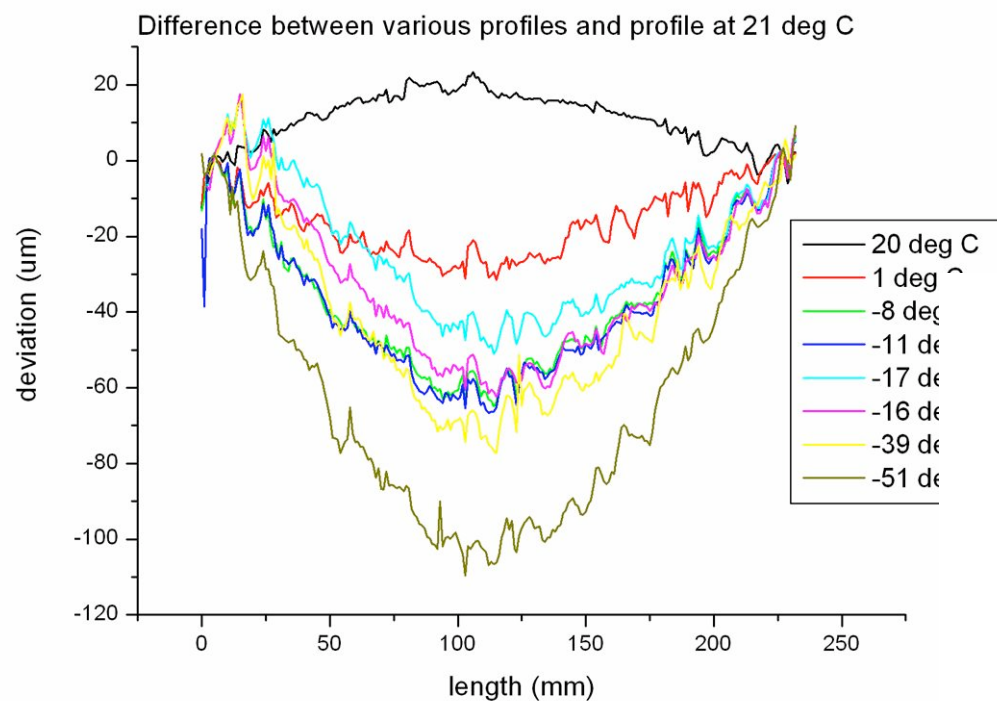
20 μm silicon

1.5 mm silicon carbide



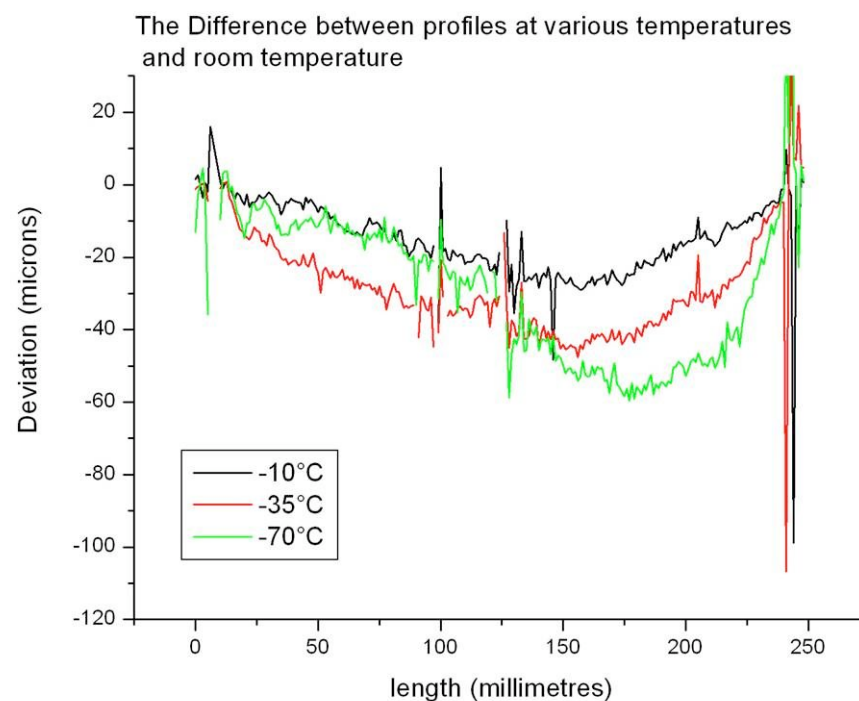


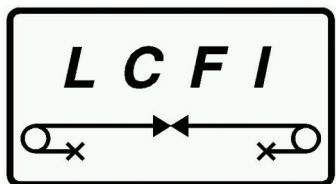
SiC Foam Results



Thin glue layer

Glue “pillars”





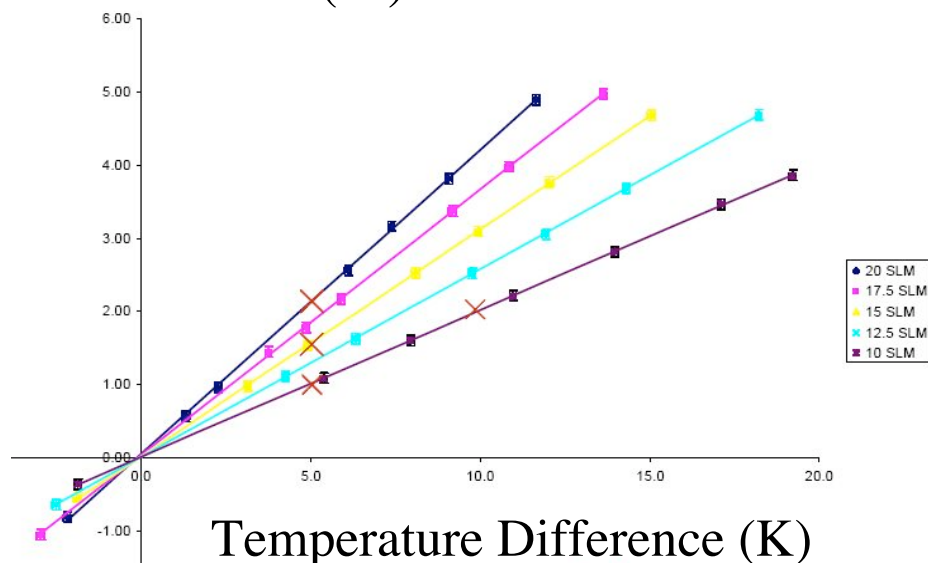
Cooling Studies



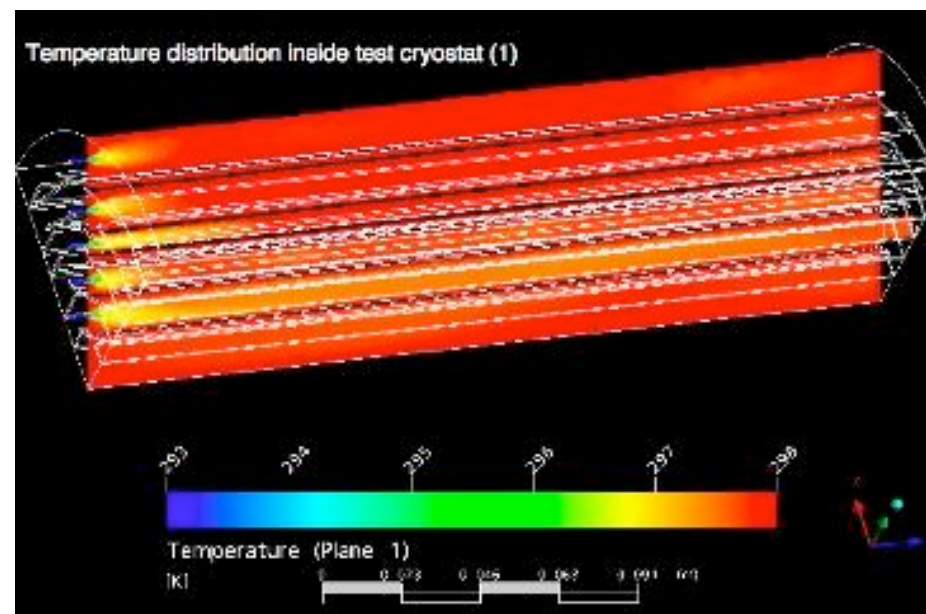
Test model of 1/4 Barrel

- Cold nitrogen cooling
- Heaters at ladder ends
- Parallel CFD simulations

Power Extracted (W)

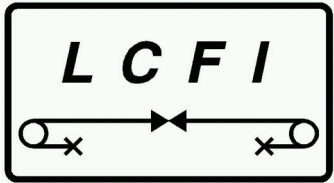


Joel Goldstein, RAL



- **Flow 5-20 SLM**
– *0.5–2 g/s whole detector*

Ringberg 2006

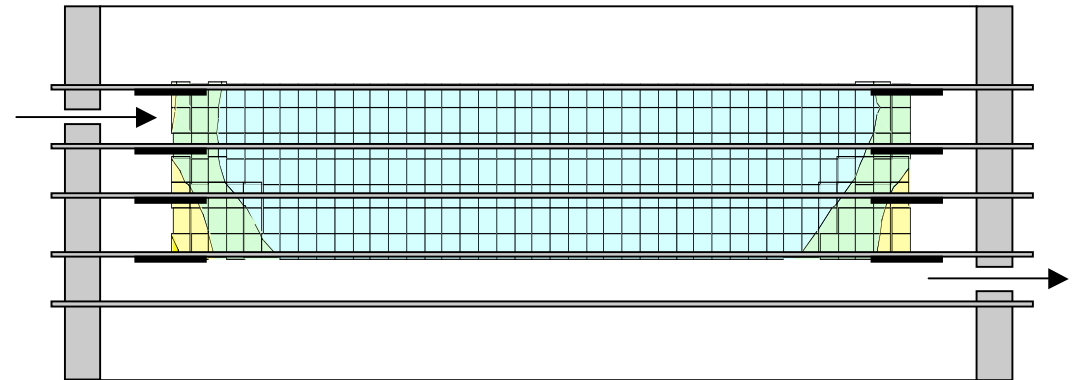


Temperature Distributions

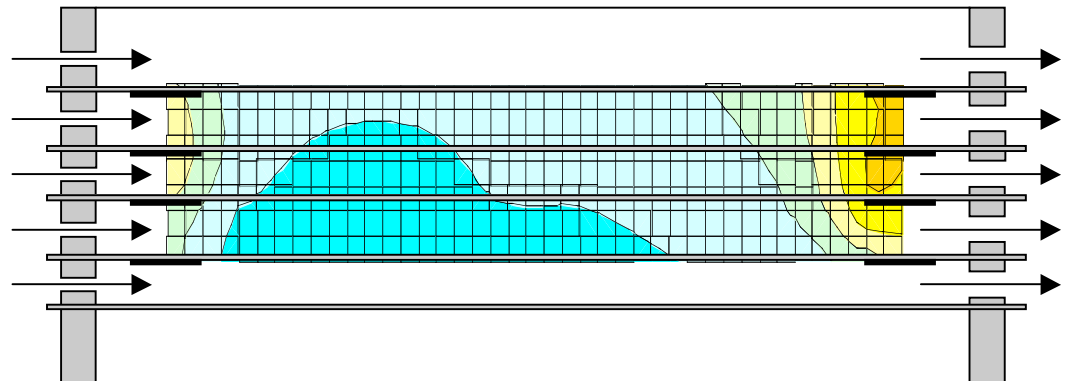
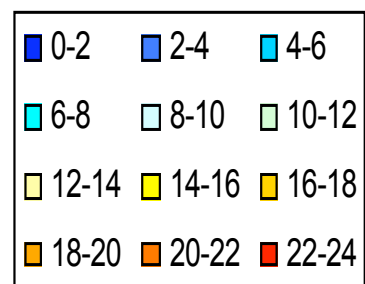


20 SLM / 8 W

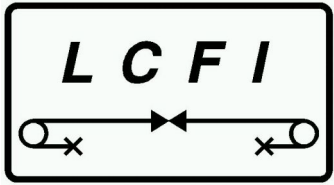
- Bulk ~ 8 K above inlet
- “Chips” 5-10 K hotter
- Layouts similar



ΔT (K)



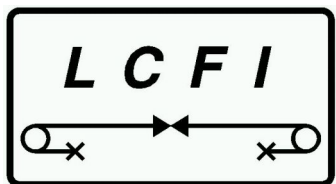
Caveat: conduction through ladders/endplates



Status & Plans

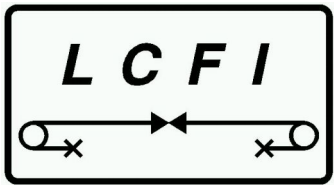


- **Ladder designs**
 - Upgrading fabrication, surveying facilities
 - Foams, CF looking promising
 - Start looking at production/aging issues
- **Cooling studies**
 - Non-conductive material
 - Match simulations
 - 30 W at low flow rates

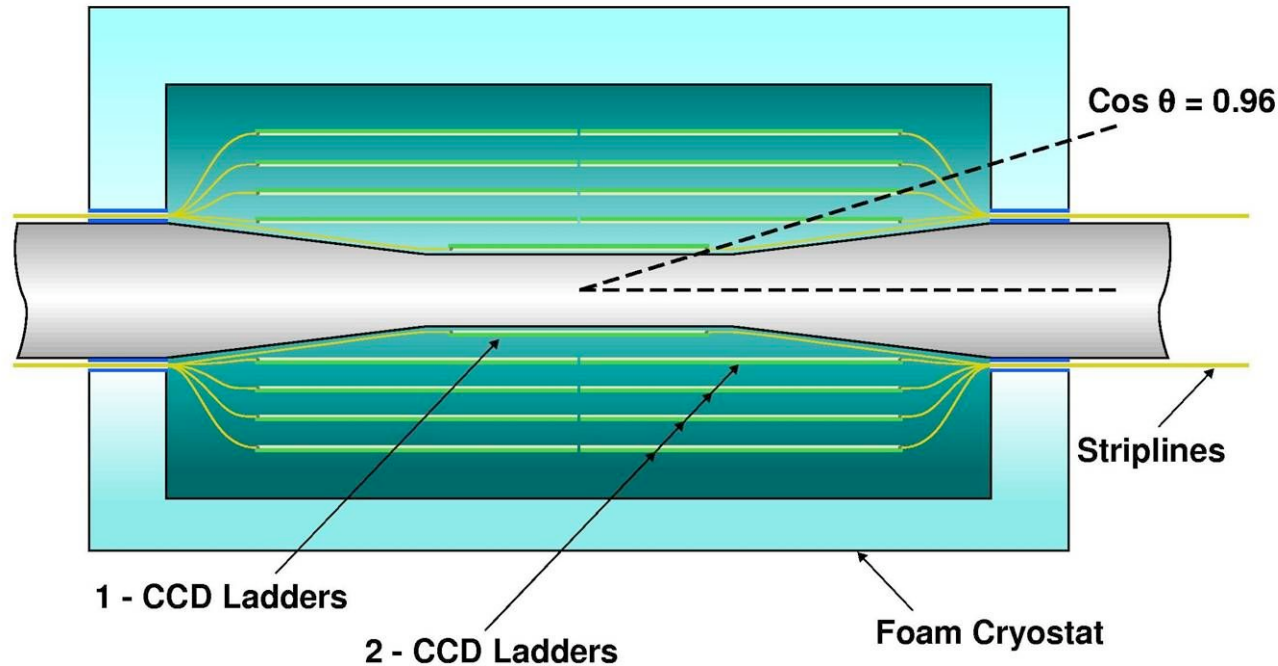


Backup Slides

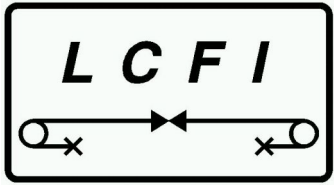




Baseline Vertex Detector



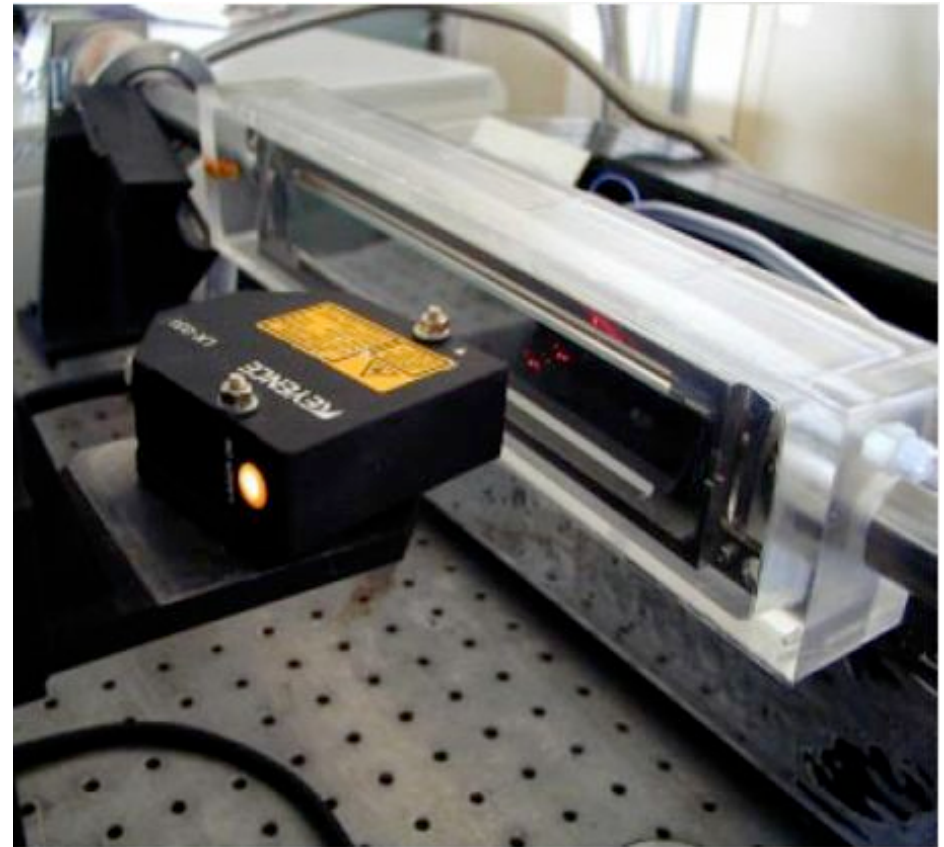
- 800 Mchannels of $20 \times 20 \mu\text{m}$ pixels in 5 layers
- Optimisation:
 - Inner radius (1.5 cm?)
 - Readout time (50 μs ?)
 - Ladder thickness (0.1% X_0 ?)

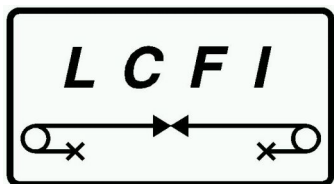


Laser Survey System



- **Laser displacement meter**
 - Z precision $\sim 1 \mu\text{m}$
- **2D motorised stage**
 - X-Y precision $< 1 \mu\text{m}$
- **Ladder in cryostat:**
 - $\Delta T \sim 100^\circ\text{C}$
- **Fast:**
 - 1D scan < 1 minute
 - Scan during cooling





Laser Calibrations

